

Title (en)

METHOD FOR PROCESSING, IN PARTICULAR SEPARATING, A SUBSTRATE BY MEANS OF LASER-INDUCED DEEP REACTIVE ETCHING

Title (de)

VERFAHREN ZUR BEARBEITUNG, INSbesondere ZUM TRENNEN EINES SUBSTRATES MITTELS LASERINDUZIERTEM TIEFENÄTZEN

Title (fr)

PROCÉDÉ D'USINAGE, EN PARTICULIER DE SÉPARATION, D'UN SUBSTRAT PAR GRAVURE PROFONDE INDUIITE PAR LASER

Publication

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Application

EP 18717553 A 20180406

Priority

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- EP 2018058882 W 20180406

Abstract (en)

[origin: WO2018210484A1] The invention relates to a method for processing a substrate by means of laser-induced deep reactive etching, wherein the laser radiation is moved along a processing line and individual pulses with a spatial laser pulse distance (d) are directed towards the substrate. An anisotropic material removal is then performed by means of etching at an etching rate (R) and an etching duration (t) under the condition $1 > d/(R*t) > 10^{-5}$.

IPC 8 full level

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B23K 103/00 (2006.01)

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C03C 15/00 (2013.01 - EP KR US); **C03C 23/0025** (2013.01 - EP KR US); **B23K 2103/54** (2018.08 - EP US)

Citation (examination)

- WO 2017038075 A1 20170309 - NIPPON SHEET GLASS CO LTD [JP]
- WO 2015018425 A1 20150212 - TRUMPF LASER & SYSTEMTECHNIK [DE]
- US 2014248757 A1 20140904 - MORIKAZU HIROSHI [JP], et al
- See also references of WO 2018210484A1

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DOCDB simple family (publication)

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JP 2020517570 A 20200618; JP 2022116133 A 20220809; JP 7396899 B2 20231212; JP 7538175 B2 20240821; KR 102260931 B1 20210604;
KR 20190132461 A 20191127; US 11065716 B2 20210720; US 2020180068 A1 20200611

DOCDB simple family (application)

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